



60-V, N-Channel NexFET™ Power MOSFETs

Check for Samples: [CSD18537NKCS](#)

FEATURES

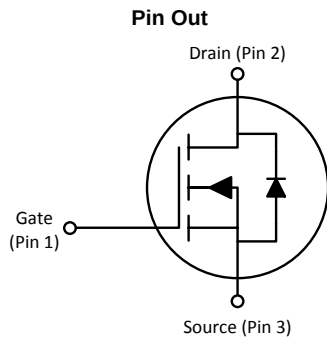
- Ultra Low Qg and Qgd
- Low Thermal Resistance
- Avalanche Rated
- Pb Free Terminal Plating
- RoHS Compliant
- Halogen Free
- TO-220 Plastic Package

APPLICATIONS

- High Side Synchronous Buck Converter
- Motor Control

DESCRIPTION

The NexFET™ power MOSFET has been designed to minimize losses in power conversion applications.



PRODUCT SUMMARY

$T_A = 25^\circ\text{C}$		TYPICAL VALUE	UNIT
V_{DS}	Drain to Source Voltage	60	V
Q_g	Gate Charge Total (10V)	14	nC
Q_{gd}	Gate Charge Gate to Drain	2.3	nC
$R_{DS(on)}$	Drain to Source On Resistance	$V_{GS} = 6\text{V}$	14 mΩ
		$V_{GS} = 10\text{V}$	11 mΩ
$V_{GS(th)}$	Threshold Voltage	3.0	V

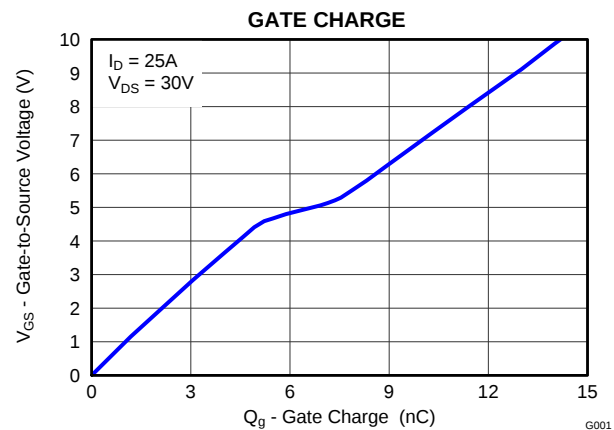
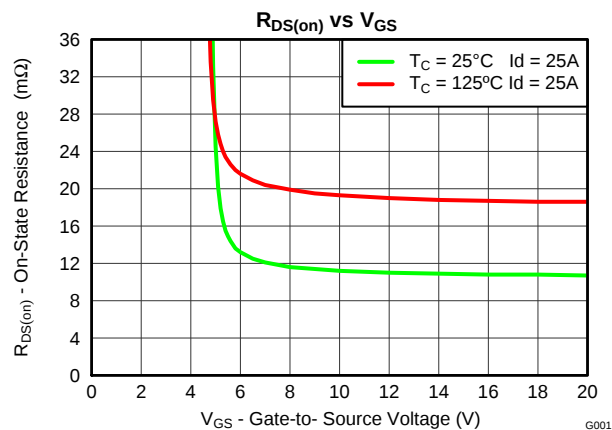
ORDERING INFORMATION

Device	Package	Media	Qty	Ship
CSD18537NKCS	TO-220 Plastic Package	Tube	50	Tube

ABSOLUTE MAXIMUM RATINGS

$T_A = 25^\circ\text{C}$		VALUE	UNIT
V_{DS}	Drain to Source Voltage	60	V
V_{GS}	Gate to Source Voltage	±20	V
I_D	Continuous Drain Current (Package limited), $T_C = 25^\circ\text{C}$	50	A
	Continuous Drain Current (Silicon limited), $T_C = 25^\circ\text{C}$	54	
	Continuous Drain Current (Silicon limited), $T_C = 100^\circ\text{C}$	34	
I_{DM}	Pulsed Drain Current ⁽¹⁾	91	A
P_D	Power Dissipation	79	W
T_J, T_{STG}	Operating Junction and Storage Temperature Range	–55 to 150	°C
E_{AS}	Avalanche Energy, single pulse $I_D = 33\text{A}, L = 0.1\text{mH}, R_G = 25\Omega$	55	mJ

(1) Pulse duration ≤300μs, duty cycle ≤2%



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These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

ELECTRICAL CHARACTERISTICS

($T_A = 25^\circ\text{C}$ unless otherwise stated)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
Static Characteristics						
BV _{DSS}	Drain to Source Voltage	V _{GS} = 0V, I _D = 250μA	60			V
I _{DSS}	Drain to Source Leakage Current	V _{GS} = 0V, V _{DS} = 48V			1	μA
I _{GSS}	Gate to Source Leakage Current	V _{DS} = 0V, V _{GS} = 20V			100	nA
V _{GS(th)}	Gate to Source Threshold Voltage	V _{DS} = V _{GS} , I _D = 250μA	2.6	3.0	3.5	V
R _{DS(on)}	Drain to Source On Resistance	V _{GS} = 6V, I _D = 25A		14	18	mΩ
		V _{GS} = 10V, I _D = 25A		11	14	mΩ
g _{fs}	Transconductance	V _{DS} = 30V, I _D = 25A		100		S
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{GS} = 0V, V _{DS} = 30V, f = 1MHz		1140	1480	pF
C _{oss}	Output Capacitance			136	177	pF
C _{rss}	Reverse Transfer Capacitance			4.0	5.2	pF
R _G	Series Gate Resistance			5.5	11.0	Ω
Q _g	Gate Charge Total (10V)	V _{DS} = 30V, I _D = 25A		14	18	nC
Q _{gd}	Gate Charge Gate to Drain			2.3		nC
Q _{gs}	Gate Charge Gate to Source			5.2		nC
Q _{g(th)}	Gate Charge at V _{th}			3.3		nC
Q _{oss}	Output Charge	V _{DS} = 30V, V _{GS} = 0V		25		nC
t _{d(on)}	Turn On Delay Time	V _{DS} = 30V, V _{GS} = 10V, I _{DS} = 25A, R _G = 0Ω		4.5		ns
t _r	Rise Time			3.2		ns
t _{d(off)}	Turn Off Delay Time			12.6		ns
t _f	Fall Time			3.9		ns
Diode Characteristics						
V _{SD}	Diode Forward Voltage	I _{SD} = 25A, V _{GS} = 0V		0.9	1	V
Q _{rr}	Reverse Recovery Charge	V _{DS} = 30V, I _F = 25A, di/dt = 300A/μs		77		nC
t _{rr}	Reverse Recovery Time			50		ns

THERMAL CHARACTERISTICS

($T_A = 25^\circ\text{C}$ unless otherwise stated)

PARAMETER		MIN	TYP	MAX	UNIT
$R_{\theta JC}$	Thermal Resistance Junction to Case			1.6	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance Junction to Ambient			62	$^\circ\text{C/W}$

TYPICAL MOSFET CHARACTERISTICS

($T_A = 25^\circ\text{C}$ unless otherwise stated)

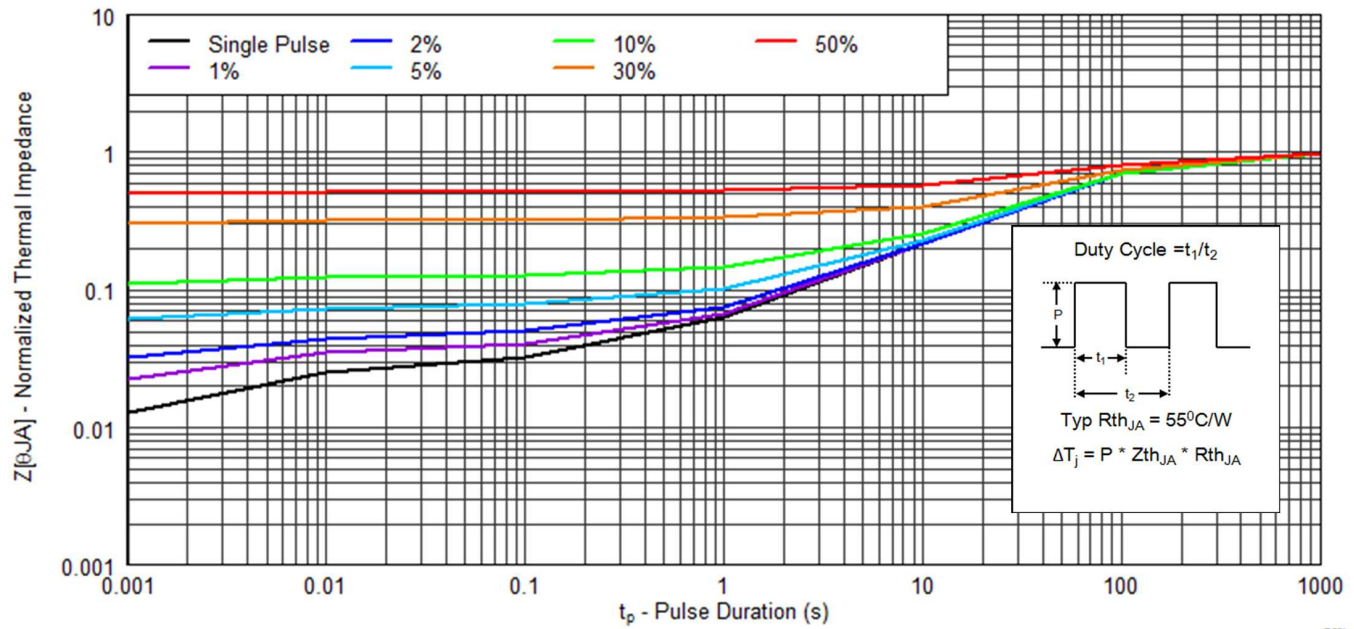


Figure 1. Transient Thermal Impedance

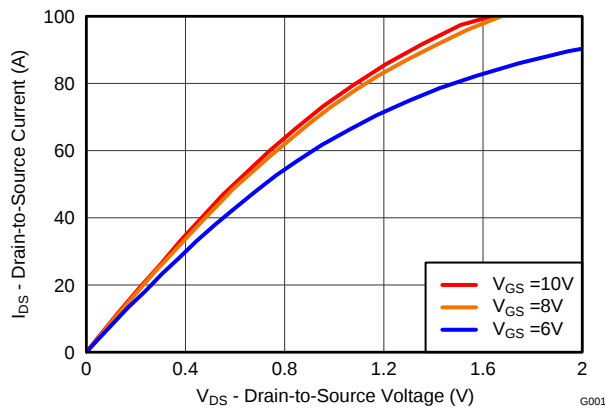


Figure 2. Saturation Characteristics

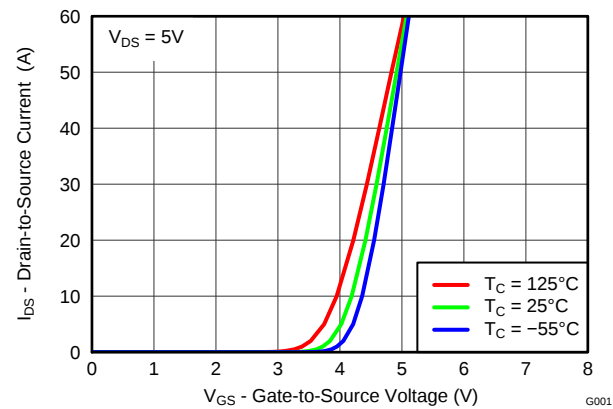


Figure 3. Transfer Characteristics

TYPICAL MOSFET CHARACTERISTICS (continued)

($T_A = 25^\circ\text{C}$ unless otherwise stated)

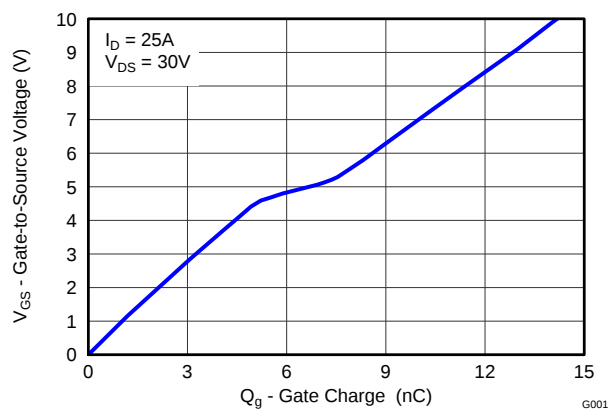


Figure 4. Gate Charge

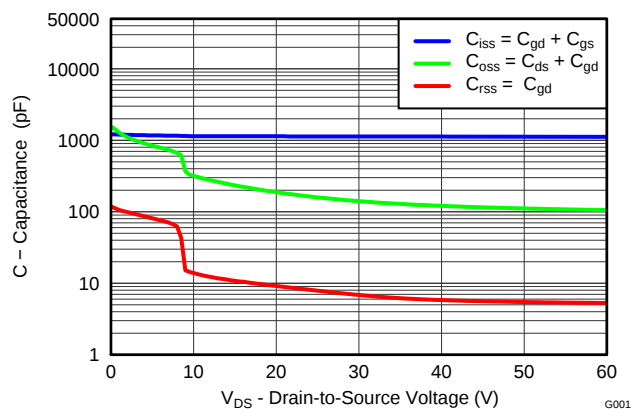


Figure 5. Capacitance

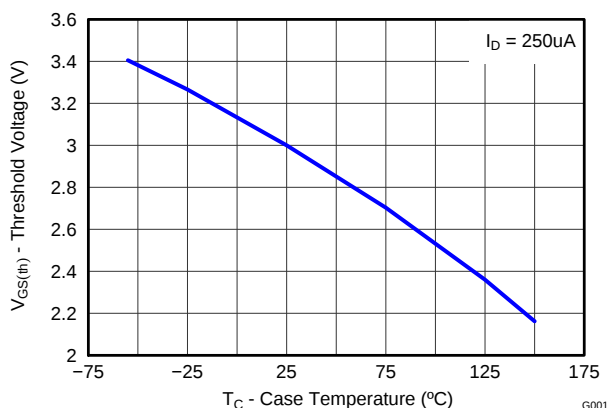


Figure 6. Threshold Voltage vs. Temperature

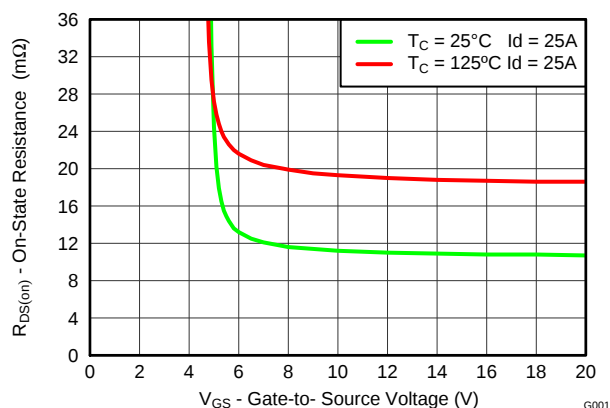


Figure 7. On-State Resistance vs. Gate-to-Source Voltage

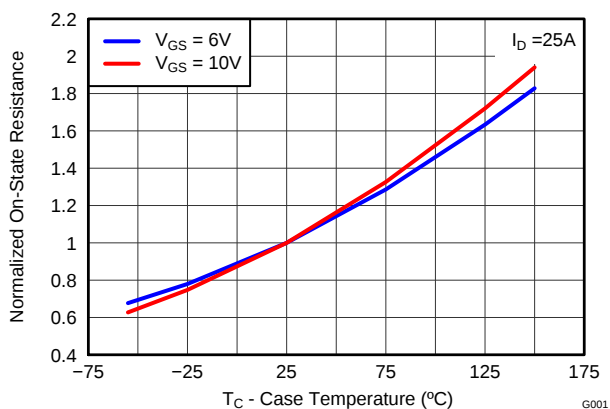


Figure 8. Normalized On-State Resistance vs. Temperature

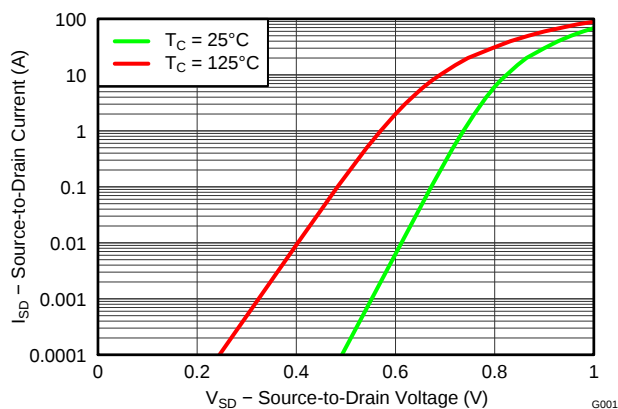


Figure 9. Typical Diode Forward Voltage

TYPICAL MOSFET CHARACTERISTICS (continued)

($T_A = 25^\circ\text{C}$ unless otherwise stated)

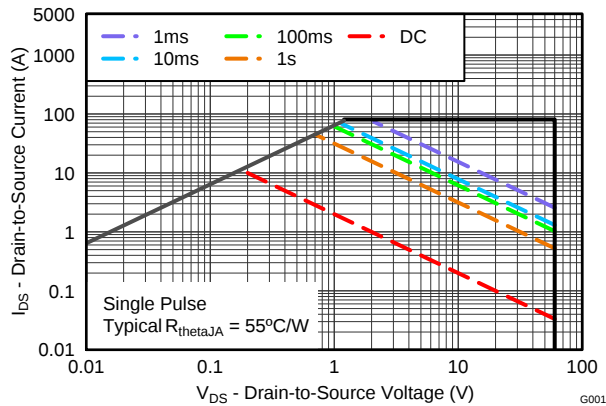


Figure 10. Maximum Safe Operating Area

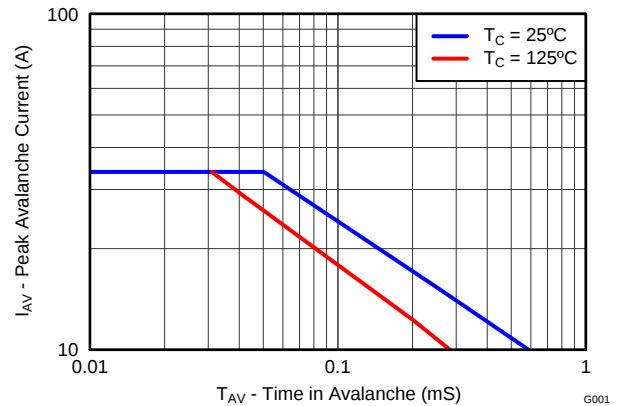


Figure 11. Single Pulse Unclamped Inductive Switching

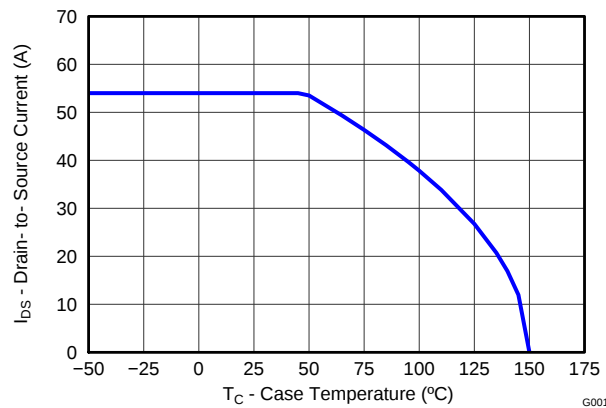
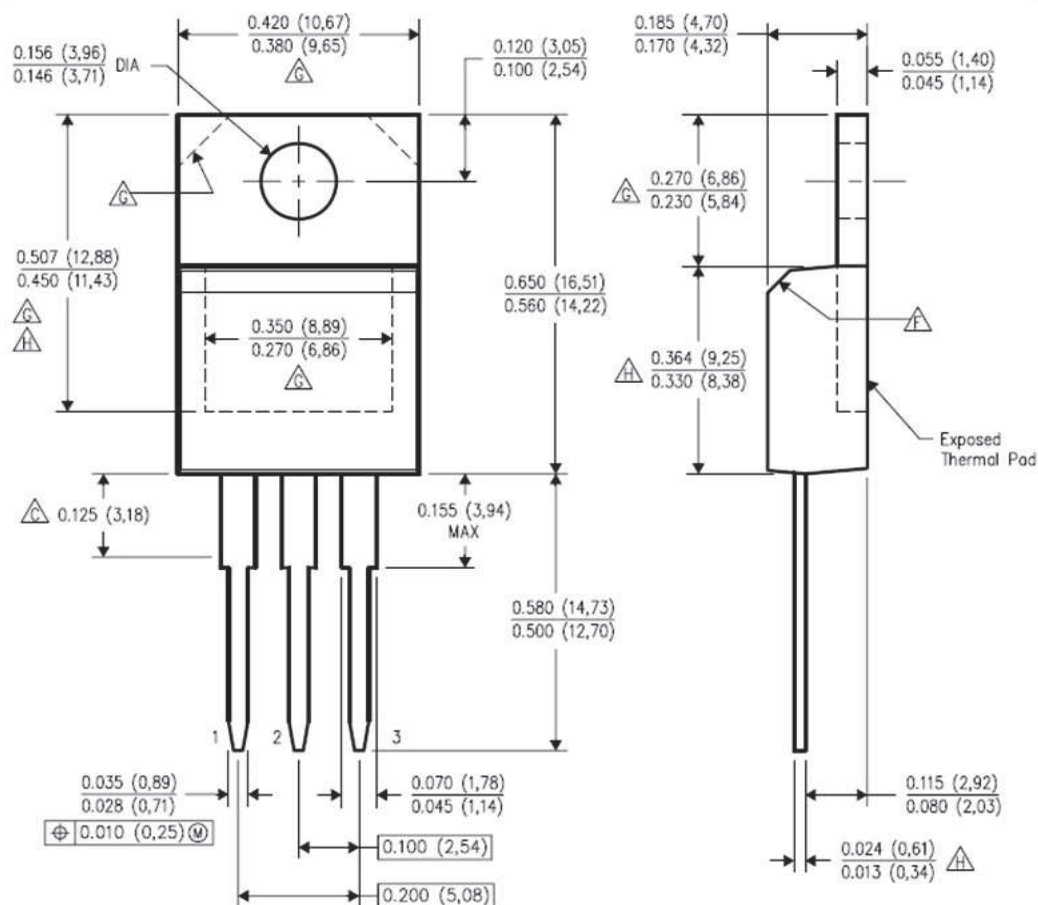


Figure 12. Maximum Drain Current vs. Temperature

MECHANICAL DATA

KCS Package Dimensions



Notes:

1. All linear dimensions are in inches
2. This drawing is subject to change without notice
3. Lead Dimensions are not controlled within "C" area
4. All lead dimensions apply before solder dip
5. The center lead is in electrical contact with the mounting tab
6. The chamfer at "F" is optional
7. Thermal pad contour at "G" optional with these dimensions
8. "H" Falls within JEDEC TO-220 variation AB, except minimum lead thickness, minimum exposed pad length, and maximum body length.

Table 1. Pin Configuration

Position	Designation
Pin 1	Gate
Pin 2 / Tab	Drain
Pin 3	Source

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
CSD18537NKCS	ACTIVE	TO-220	KCS	3	50	Pb-Free (RoHS Exempt)	CU SN	N / A for Pkg Type	-55 to 150	18537N	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

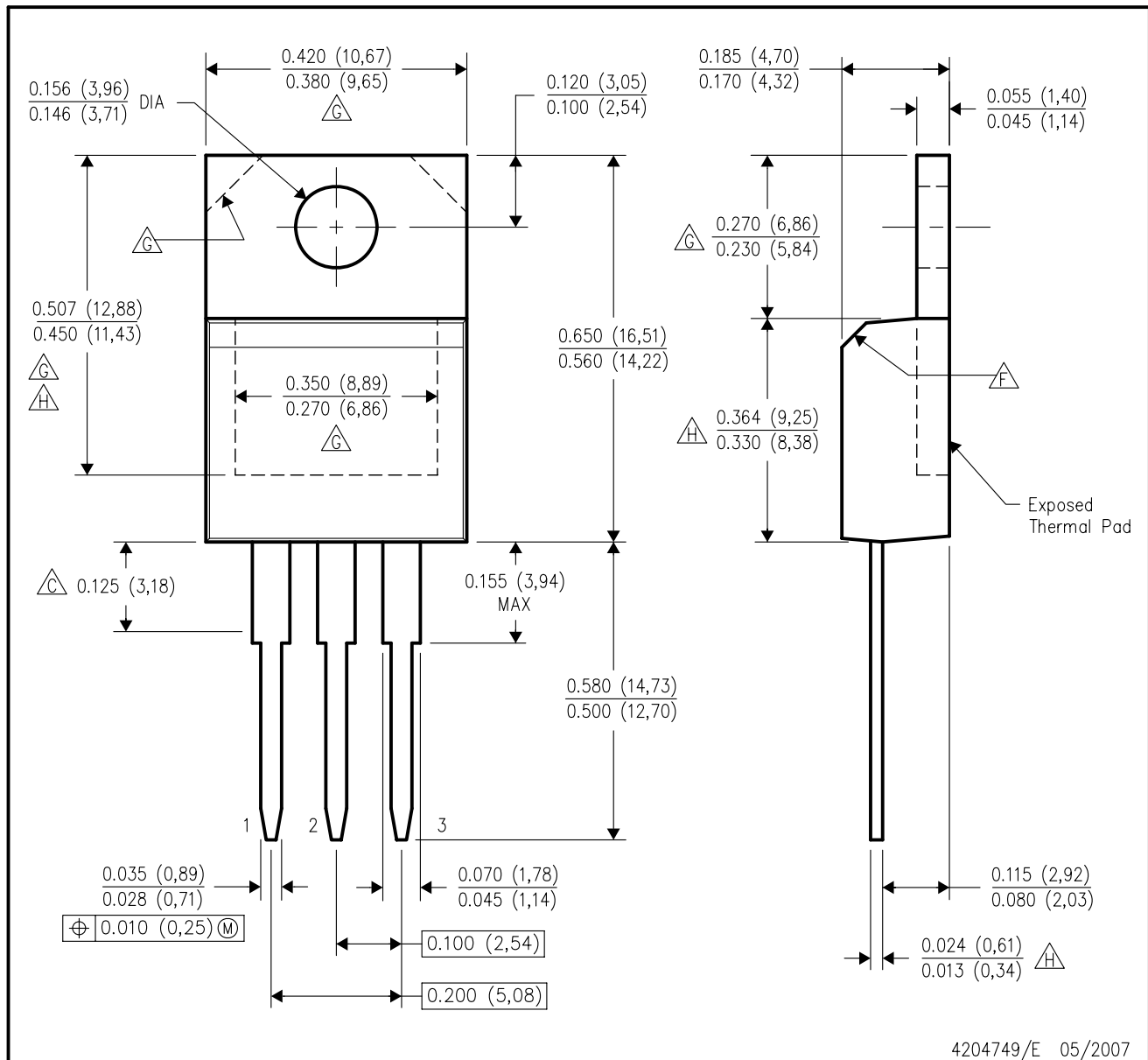
(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

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KCS (R-PSFM-T3)

PLASTIC FLANGE-MOUNT PACKAGE



4204749/E 05/2007

NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Lead dimensions are not controlled within this area.
- D. All lead dimensions apply before solder dip.
- E. The center lead is in electrical contact with the mounting tab.
- F. The chamfer is optional.
- G. Thermal pad contour optional within these dimensions.
- H. Falls within JEDEC TO-220 variation AB, except minimum lead thickness, minimum exposed pad length, and maximum body length.

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